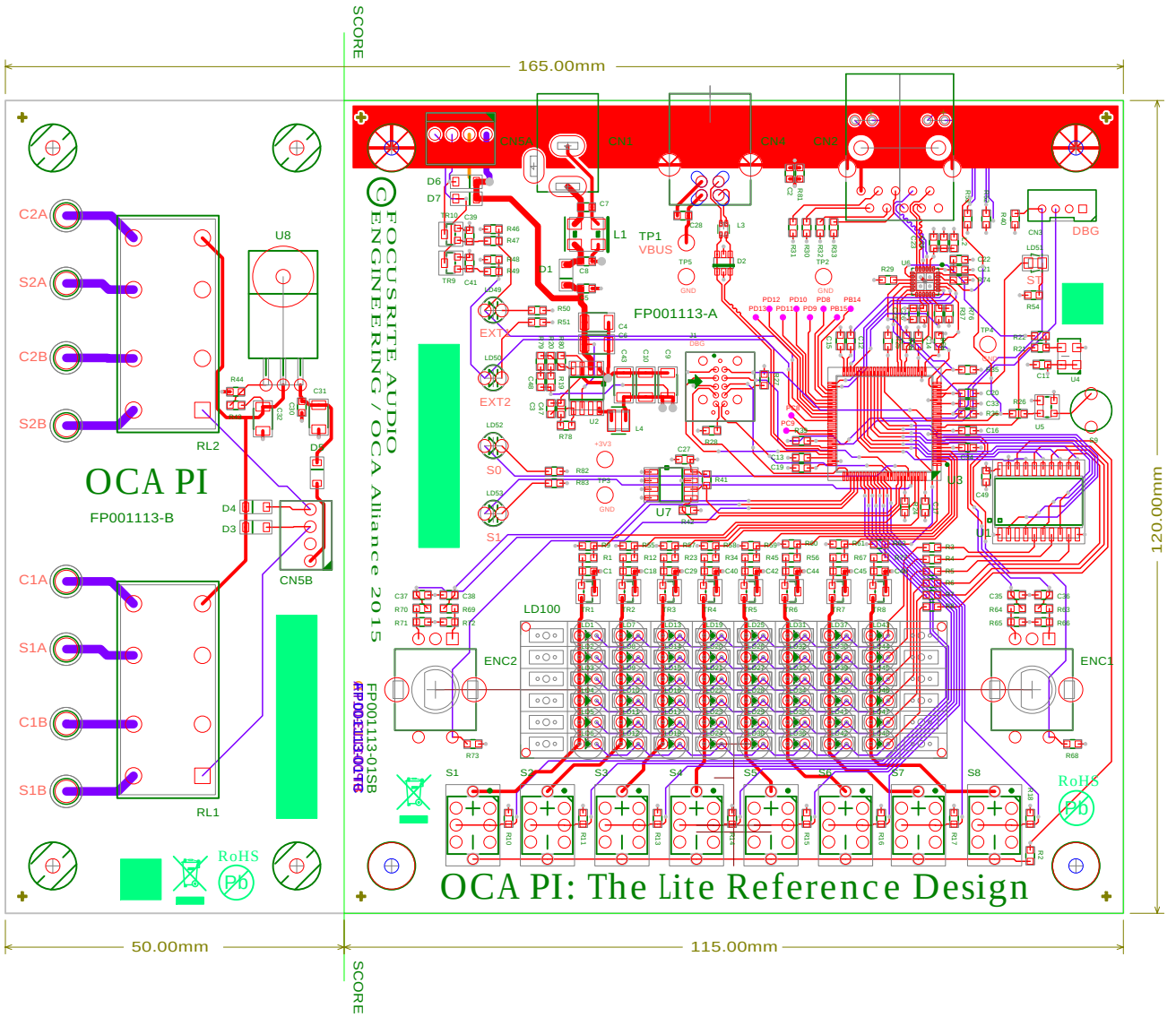
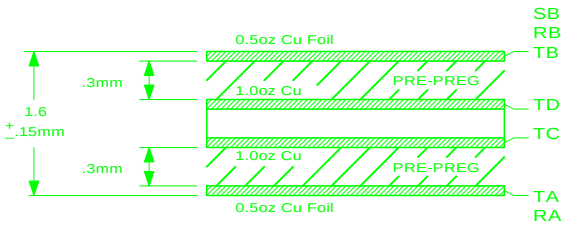


PCB BUILD INFORMATION

NOT TO SCALE



TOLERANCES:

BOARD PROFILE +/- 0.15MM
HOLE DIAMETER +/- 0.076MM
TRUE HOLE POSITION +/-0.05MM
BOW NOT TO EXCEED 1% OF LENGTH.
MATERIAL TO BS4584 PT2
GRADE EP-GC-CU-2 1.6MM
35UM MIN. FINISHED
SURFACE THICKNESS.

PLATED THROUGH HOLE-PLATING
THICKNESS:
COPPER 0.018MM MIN, 0.02MM AVG
TIN 0.0076MM (MIN)

SMT BOARD: Y

SM PADS COUNT: 505 TOP SIDE
SM PADS COUNT: 0 MAX SIDE

DRILL DETAILS (MM DIA)

REF.	SIZE	COUNT	PTH

SEE REPORT FILE
FP001113-01.REP

MANUFACTURING PACKAGE

MATERIAL & TRACK SIDES:
SEE STACK DRAWING

SOLDER RESIST:------ Y
SEPARATE RESIST FOR
SIDE B---------- Y
COMPONENT IDENT----- Y
DRILL DRG. ---------- Y
CONTROL IMPEDANCE --
PTH ---------- Y
PLUG VIAS FOR
BGA / QFN DEVICES - N

OCA PI
FP001113-01-DR
DRILL DRAWING

NOTES:

1) BOARDS TO BE MANUFACTURED TO BS9763
2) ALL HOLES DRILLED IN ONE PASS.
3) ALL HOLES TO BE FINISHED SIZE.
4) SOLDER RESIST & IDENT TO BS6096
5) BOARDS TO BE PHOTO IMAGE SOLDER RESIST.
6) RESIST TO BE RED IN COLOUR.
7) SILKSCREEN IDENT TO BE WHITE.
8) BOARDS TO BE IMMERSION GOLD FINISH.
9) BOARDS TO BE BARE BOARD TESTED.